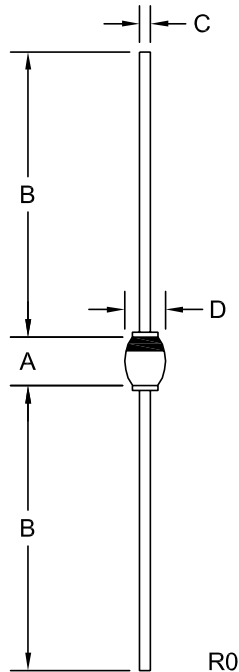


Package Details - GPR-4AM

Mechanical Drawing



DIMENSIONS				
SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.165	0.189	4.20	4.80
B	1.024	---	26.00	---
C	0.037	0.042	0.95	1.06
D	0.130	0.175	3.30	4.45

GPR-4AM (REV: R0)

Lead Code:
Cathode band

Packing options:

Bulk - Packing Code: D

D = White corrugated box with black conductive coating (surface resistivity of $<10^5$ ohms per square).

Bulk Packing Quantity: 500

Tape and Reel - Packing Code: A

A = Axial taped and reeled in accordance with EIA-296-E. If required, individual reels placed in poly antistatic coated bags (surface resistivity of $>10^9$ and $<10^{13}$ ohms per square).

Tape and Reel Packing Quantity: 1,600

Material Composition Specification

GPR-4AM Case



Device average mass 947 mg
 Fluctuation margin +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.26%	2.48	Si	7440-21-3	0.26%	2.48	2,619
axial lead	wire	79.56%	753.39	Cu	7440-50-8	79.51%	752.94	795,079
				Zn	7440-66-6	0.05%	0.45	475
	moly slug	14.21%	134.6	Mo	7439-98-7	14.21%	134.6	142,133
die attach	solder	0.57%	5.38	Cu	7440-50-8	0.45%	4.3	4,541
				Ag	7440-22-4	0.09%	0.81	855
				P	7723-14-0	0.03%	0.27	285
encapsulation	glass	4.01%	38	Zn	7440-66-6	1.93%	18.24	19,260
				O	7782-44-7	1.47%	13.95	14,730
				B	7440-42-8	0.38%	3.6	3,801
				Si	7440-21-3	0.15%	1.45	1,531
				Pb	7439-92-1	0.08%	0.76	803
plating*	tin/lead process	1.39%	13.17	Sn	7440-31-5	1.18%	11.2	11,827
				Pb	7439-92-1	0.21%	1.97	2,080
	matte tin	1.39%	13.17	Sn	7440-31-5	1.39%	13.17	13,907

*For Lead Free plating, add suffix "LEAD FREE" to part number.
 For Tin/Lead plating, add suffix "TIN/LEAD" to part number.
 No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R4 (10-September 2013)